

Appl No. 10/785,252  
Response Date: 1/3/06  
Response to Office Action

### **AMENDMENTS TO THE CLAIMS**

Please amend the claims as follows. This listing of the claims will replace all prior versions, and listings, of claims in the application:

#### **Listing of Claims:**

1. (currently amended) An exposure apparatus which exposes a substrate through a pattern of an original plate, comprising:

a piping ~~part~~ made of resin; and

means for feeding into the piping liquid or gas having a predetermined temperature, wherein the predetermined temperature is set to be between 5 °C and 18 °C  
~~controlling the temperature of the resin part at a predetermined temperature or lower.~~

2. (currently amended) An exposure apparatus according to Claim 1, further comprising a stage for moving the original plate,

wherein the liquid or gas cools the stage for the original plate and flows through the piping, the resin part being piping through which a fluid for cooling the stage for the original plate flows.

3. (currently amended) An exposure apparatus according to Claim 1, further comprising a stage for moving a substrate,

wherein the liquid or gas cools the stage for the substrate and flows through the piping ~~the resin part being piping through which a fluid for cooling the stage for the substrate flows.~~

Appl No. 10/785,252  
Response Date: 1/3/06  
Response to Office Action

4. (original) An exposure apparatus according to Claim 1, wherein the predetermined temperature is lower than the temperature of the substrate.

5. (original) An exposure apparatus according to Claim 1, further comprising a stage for moving the original plate; and

a chamber enclosing the stage for the original plate,

wherein the predetermined temperature is lower than the temperature of an inner-wall of the chamber.

6. (original) An exposure apparatus according to Claim 1, further comprising a stage for moving a substrate; and

a chamber enclosing the stage,

wherein the predetermined temperature is lower than the temperature of an inner-wall of the chamber.

7. (canceled)

8. (original) An exposure apparatus according to Claim 1, wherein the predetermined temperature is lower by at least 5°C than the temperature of the substrate.

Appl No. 10/785,252  
Response Date: 1/3/06  
Response to Office Action

9. (currently amended) An exposure apparatus according to Claim 1, wherein ~~the resin part is piping,~~ and the piping contains a first pipe through which a first fluid flows, and a second pipe through which a second fluid flows.

10. (original) An exposure apparatus according to Claim 9, wherein the temperature of the first fluid is different than the temperature of the second fluid.

11. (original) An exposure apparatus according to Claim 9, wherein the piping is formed in such a manner that the second pipe encloses the first pipe.

12. (original) An exposure apparatus according to Claim 10, wherein the temperature of the first fluid is lower than the temperature of the second fluid.

13. (original) An exposure apparatus according to Claim 9, wherein the temperature of the second fluid is lower than the predetermined temperature.

14. (original) An exposure apparatus according to Claim 9, wherein the temperature of the second fluid is lower than the temperature of the substrate.

15. (canceled)

Appl No. 10/785,252  
Response Date: 1/3/06  
Response to Office Action

16. (currently amended) An exposure apparatus according to Claim 24, ~~wherein the resin part is piping, and the temperature control means has a cooling mechanism to cause a fluid having a lower temperature than the temperature of the substrate to flow through the piping and further comprising a heating mechanism for heating the stage for the original plate at least a part of the cooling mechanism.~~

17. (original) An exposure apparatus according to Claim 16, wherein the heating mechanism contains a Peltier device.

18. (original) An exposure apparatus according to Claim 5, wherein the inside of the chamber is kept in a vacuum state.

19. (original) An exposure apparatus according to Claim 6, wherein the inside of the chamber is kept in a vacuum state.

20. (original) A method of producing a device fabricating method comprising the steps of:

    exposing a substrate by means of using an exposure apparatus according to Claim 1; and  
    developing the exposed substrate.

Appl No. 10/785,252  
Response Date: 1/3/06  
Response to Office Action

21. (new) An exposure apparatus according to Claim 1, further comprising an optical element coupled to be driven,

wherein the liquid or gas cool the optical element and flow through the piping.

22. (new) An exposure apparatus according to Claim 3, further comprising a heating mechanism for heating the stage for the substrate.